

What is claimed is:

1. An adhesive tape for removing a resist, which comprises: a supporting base material; and a curing adhesive layer provided on the supporting base material, wherein the curing adhesive layer exhibits an initial tensile modulus of not smaller than 10 MPa at 100°C after cured.

2. An adhesive tape for removing a resist, which comprises: a supporting base material; and an adhesive layer provided on the supporting base material, wherein the supporting layer has a flexural stiffness per unit width of not smaller than 1×10^{-4} N·m.

3. The adhesive tape for removing a resist according to Claim 1, wherein the supporting layer has a flexural stiffness per unit width of not smaller than 1×10^{-4} N·m.

4. The adhesive tape for removing a resist according to Claim 1, wherein the curing adhesive layer exhibits an initial tensile modulus of from 20 MPa to 200 MPa at 100°C after cured.

5. The adhesive tape for removing a resist according to Claim 2, wherein the supporting layer has a flexural stiffness per unit width of 5×10^{-4} to 1×10^{-1} N·m.

6. A process for removing a resist, which comprises:
applying an adhesive tape according to Claim 1 to an article
on which a resist film image is present; and peeling off the
adhesive tape and the resist film image together from the
5 article.

7. The process for removing a resist according to Claim
6, wherein the peeling is effected under heating at a temperature
of not lower than 50°C.

8. The process for removing a resist according to Claim
6, wherein a resist film having the resist film image has a
thickness exceeding 10 μm .